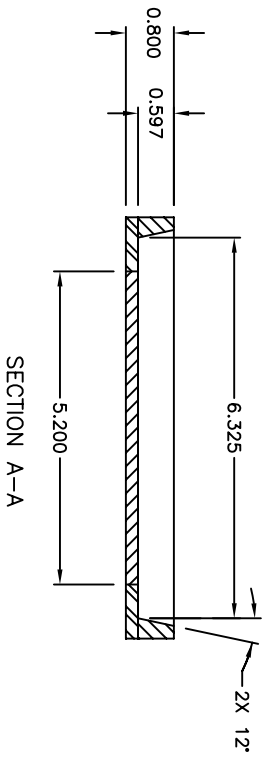
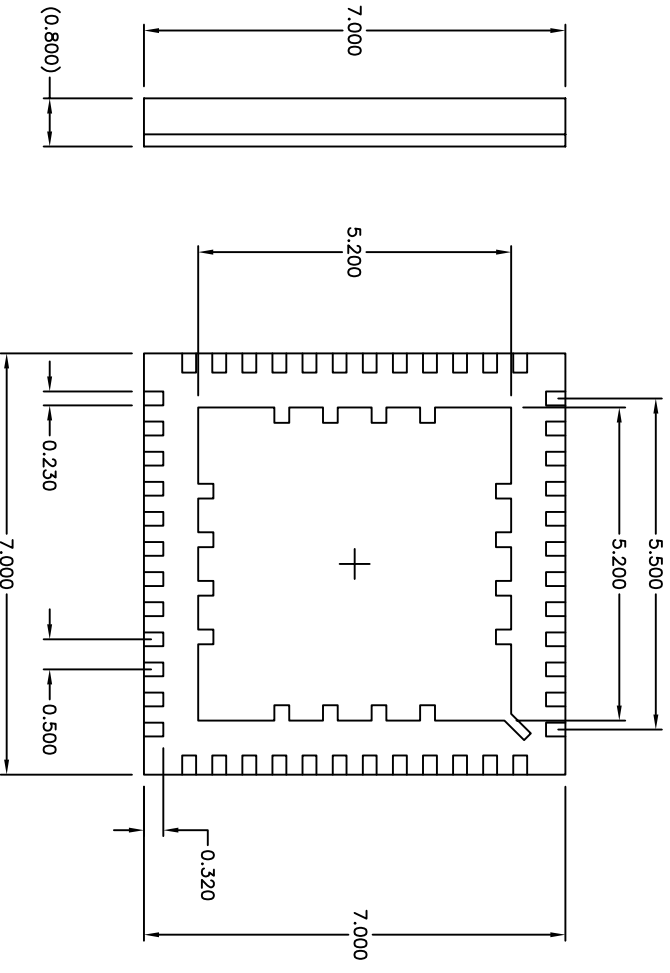
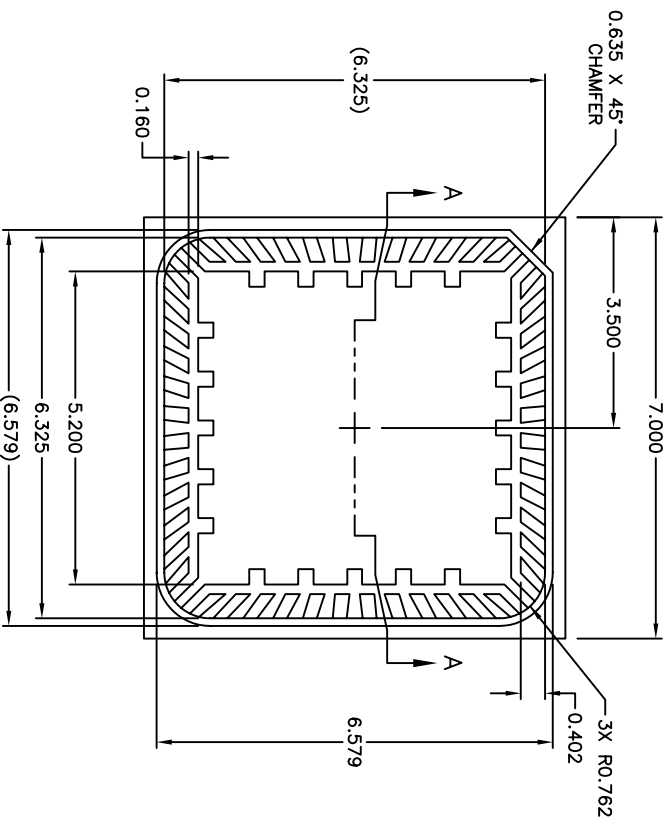


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| REVISIONS | | | APPROVED |
|-----------|----------|--------------------|------------|
| ECN NO. | DATE | DESCRIPTION | |
| 10501 | 10/27/05 | PRODUCTION RELEASE | D.BENANDIO |



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, FH 194.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 5.200 X 5.200.
 6. JEDEC OUTLINE: MO-220 (YKKD).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
 TOLERANCES ARE: XXXX ± 0.15
 ANGLES: ± 1°
 DO NOT SCALE DRAWING

| | | | |
|----------|--------------|------|----------|
| DRAWN BY | W. GRIFFITTS | DATE | 10/26/05 |
| APP BY | P. FLASKERUD | DATE | 10/26/05 |
| CUSTOMER | ---- | | |

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48 Lead 7mm x 7mm
 MLP Open-Pak

| | | |
|----------|------------------------|-----|
| SIZE | PART NO. | REV |
| A | MLP7X7-48-OP-02 | 2 |
| SCALE | NONE | |
| CAD FILE | MLP7X7-48-OP-02-R2.DWG | |
| SHEET | 1 OF 1 | |

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